

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT3148895

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
LAPIS SEMICONDUCTOR CO., LTD	10/20/2014

RECEIVING PARTY DATA

Name:	HPLP TECHNOLOGIES INC.
Street Address:	15090 AVENUE OF SCIENCE
Internal Address:	SUITE 103
City:	SAN DIEGO
State/Country:	CALIFORNIA
Postal Code:	92128

PROPERTY NUMBERS Total: 14

Property Type	Number
Patent Number:	6890796
Patent Number:	8018076
Patent Number:	7663251
Patent Number:	7365439
Patent Number:	7129587
Patent Number:	6661099
Patent Number:	6175159
Patent Number:	6538319
Patent Number:	6225694
Patent Number:	7832648
Patent Number:	7503479
Patent Number:	7299973
Patent Number:	7137557
Patent Number:	6896186

CORRESPONDENCE DATA

Fax Number: (613)688-4894

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Email: sscarborough@wilan.com

Correspondent Name: HPLP TECHNOLOGIES INC.

PATENT

Address Line 1: 15090 AVENUE OF SCIENCE
Address Line 2: SUITE 103
Address Line 4: SAN DIEGO, CALIFORNIA 92128

ATTORNEY DOCKET NUMBER: LAPIS SEMICONDUCTOR

NAME OF SUBMITTER: SARAH SCARBOROUGH

SIGNATURE: //Sarah Scarborough//

DATE SIGNED: 12/16/2014

Total Attachments: 3

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TRANSFER ASSIGNMENT DOCUMENTS

THIS ASSIGNMENT is effective as of October 31, 2014 by and between HPLP Technologies Inc., a Delaware corporation ("Purchaser") and Lapis Semiconductor Co., Ltd., a corporation existing under the laws of Japan ("Seller").

WHEREAS in this Assignment, "Patents" means:

- (a) a specific patent or patent application listed in Exhibit "A";
- (ii) a patent or patent application to, from or through which any patent or patent application described in (i) claims priority; and
- (iii) any foreign patent, foreign patent application or foreign counterpart of any patent or patent application described in (i) or (ii) that has substantially the same specification and claims substantially the same invention as such patent or patent application.

AND WHEREAS Seller owns all interest, right, title, property and benefit in and to each of the Patents and has agreed to assign all interest, right, title, property and benefit in and to each of the Patents to Purchaser;

NOW, THEREFORE, in consideration of good and valuable consideration, the receipt and sufficiency of which are hereby expressly acknowledged, Seller hereby sells, assigns, transfers, conveys and sets over to Purchaser (1) all of Seller's interest, right, title, property and benefit in and to each of the Patents, (2) the sole right to collect any damages for past, current and future infringement of each of the Patents to the extent not covered by license agreements or forbearances existing as of the date hereof that have been expressly disclosed to Purchaser prior to the date hereof and (3) the right to sue for past, current and future infringement of each of the Patents.

IN WITNESS WHEREOF, Seller has caused this Assignment to be executed effective as of the date first written above by its duly authorized officer.

Oct. 20 2014

Signed: Akio Kita
Name: Akio Kita
Title: Director, Administrative Headquarters

Country of Japan)
City of Yokohama)
)
)

ATTESTATION OF SIGNATURE PURSUANT TO 28 U.S.C. 1746

The undersigned witnessed the signature of Akio Kita to the above Assignment of Patent Rights on behalf of Lapis Semiconductor Co., Ltd. and makes the following statements:

- 1. I am over the age of 18 and competent to testify as to the fact in this Attestation block if called upon to

do so.

2. Akio Kita is personally known to me (or proved to me on the basis of satisfactory evidence) and appeared before me on Oct. 20th, 2014 to execute the above Assignment of Patent Rights on behalf of Lapis Semiconductor Co., Ltd.

3. Akio Kita subscribed to the above Assignment of Patent Rights on behalf of Lapis Semiconductor Co., Ltd.

I declare under penalty of perjury under the laws of the United States of America that the statements made in the three (3) numbered paragraphs immediately above are true and correct.

EXECUTED on Oct. 20, 2014
(date)

Print name: Makoto Takashima

Exhibit "A"
Patents

Family Index	Juris.	Registered Number	Title	Estimated Termination Date
1	US	US6890796	Method of manufacturing a semiconductor package having semiconductor device mounted thereon and elongate opening through which electrodes and patterns are connected	04/20/2018
1	US	US8018076	Semiconductor device, semiconductor package for use therein, and manufacturing method thereof	04/20/2018
1	US	US7663251	Semiconductor device, semiconductor package for use therein, and manufacturing method thereof	04/20/2018
1	US	US7365439	Semiconductor device, semiconductor package for use therein, and manufacturing method thereof	04/20/2018
1	US	US7129587	Semiconductor device, semiconductor package for use therein, and manufacturing method thereof	04/20/2018
1	US	US6661099	Semiconductor device, semiconductor package for use therein, and manufacturing method thereof	04/20/2018
1	US	US6175159	Semiconductor package	04/20/2018
1	KR	KR100368698B1		7/13/2018
1	KR	KR19990013820A		
1	JP	JPH1140694A		
1	TW	TW376556B		04/20/2018
2	US	US6538319	Semiconductor device	08/28/2018
2	US	US6225694	Semiconductor device	08/28/2018
2	US	US2001008301A1		
2	US	US6225694B1		
2	US	US6538319B2		
2	KR	KR100404159B1		09/01/2018
2	KR	KR19990029419A		
2	JP	JP3834426B2		06/17/2018
2	JP	JPH11145333A		
3	US	US7832648	Semiconductor device and an information management system therefor	04/01/2018
3	US	US7503479	Semiconductor device and an information management system therefor	04/01/2018
3	US	US7299973	Semiconductor device and an information management system therefor	04/01/2018
3	US	US7137557	Semiconductor device and an information management system therefor	04/01/2018
3	US	US6896186	Semiconductor device and an information management system thereof	04/01/2018
3	TW	TW378346B		03/08/2018
3	KR	KR19990006383A		
3	JP	JPH1126333A		
3	JP	JP2003178940A		
3	JP	JP2007059948A		
3	JP	JP2011124587A		
3	JP	JP5298141B		06/27/2017